

## Solution to Site Problem

### Dot and Dab Incorrect Application

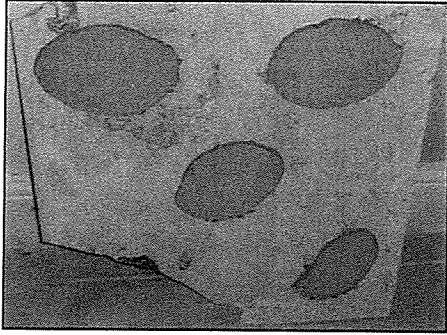


Figure 1

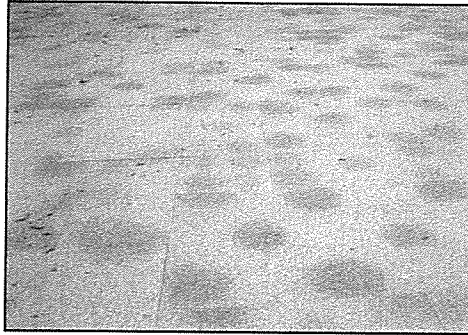


Figure 2

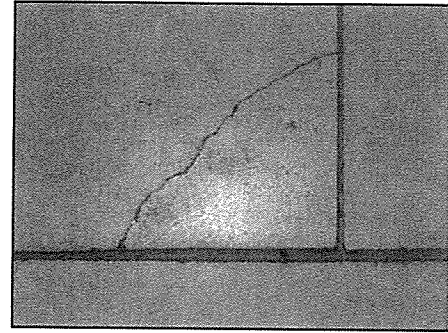


Figure 3

#### What does it look like?

Figure 1 – The tile backs and substrate will have four or five rounded columns of adhesive with substantial air voids in between.

Figure 2 – Spots of adhesive can be seen through the tile.

Figure 3 – Tiles crack in areas that are unsupported due to point loads such as heels or furniture.

#### What is the cause?

This is caused by using an incorrect application technique. Often tilers will use the dot and dab technique to get tile levels correct by building mounts of adhesive and tapping down until level. This leaves only small areas of the tiles and substrate in contact with the adhesive and leaves large air voids.

#### What is the remedy?

Often it is difficult to remove the tile and adhesive without damaging the substrate.

A time and cost effective solution for floors is to remove the tiles and loose adhesive, prime with **weber PR360** and then cover with **weber.floor flex** leveling compound (10mm minimum on wooden substrates). The tiles can then be re-fixed using the correct application technique to ensure 100% coverage.

For walls it is often quicker to remove and replace the boards and then re-fix using the correct application technique.